



<IGBT Modules>

CM1000DX-24T/CM1000DXP-24T

**HIGH POWER SWITCHING USE
INSULATED TYPE**

DX		Collector current I_C 1 0 0 0 A Collector-emitter voltage V_{CES} 1 2 0 0 V Maximum junction temperature T_{vjmax} 1 7 5 °C <ul style="list-style-type: none"> ● Flat base type ● Copper base plate (Nickel-plating) ● RoHS Directive compliant ● Tin-plating pin terminals
DXP		Collector current I_C 1 0 0 0 A Collector-emitter voltage V_{CES} 1 2 0 0 V Maximum junction temperature T_{vjmax} 1 7 5 °C <ul style="list-style-type: none"> ● Flat base type ● Copper base plate (Nickel-plating) ● RoHS Directive compliant ● Tin-plating pressfit terminals
dual switch (half-bridge)		<ul style="list-style-type: none"> ● UL Recognized under UL1557, File No. E323585

APPLICATION

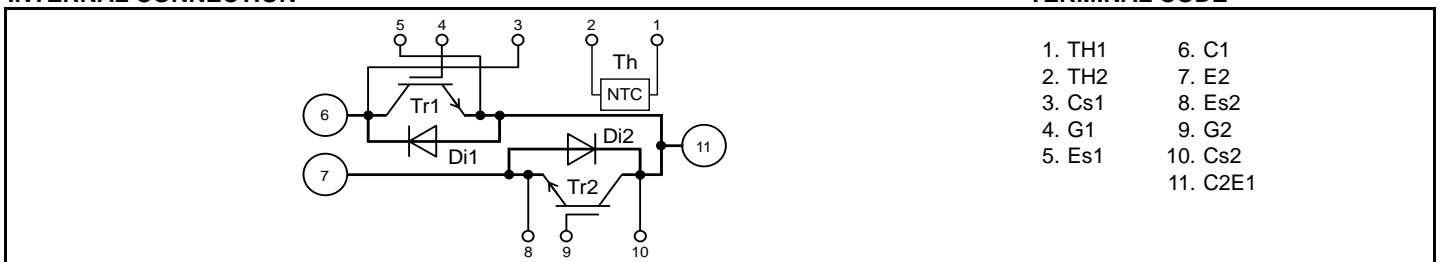
AC Motor Control, Motion/Servo Control, Power supply, etc.

OPTION (Below options are available.)

- PC-TIM (Phase Change Thermal Interface Material) pre-apply
- V_{CEsat} selection for parallel connection

INTERNAL CONNECTION

TERMINAL CODE

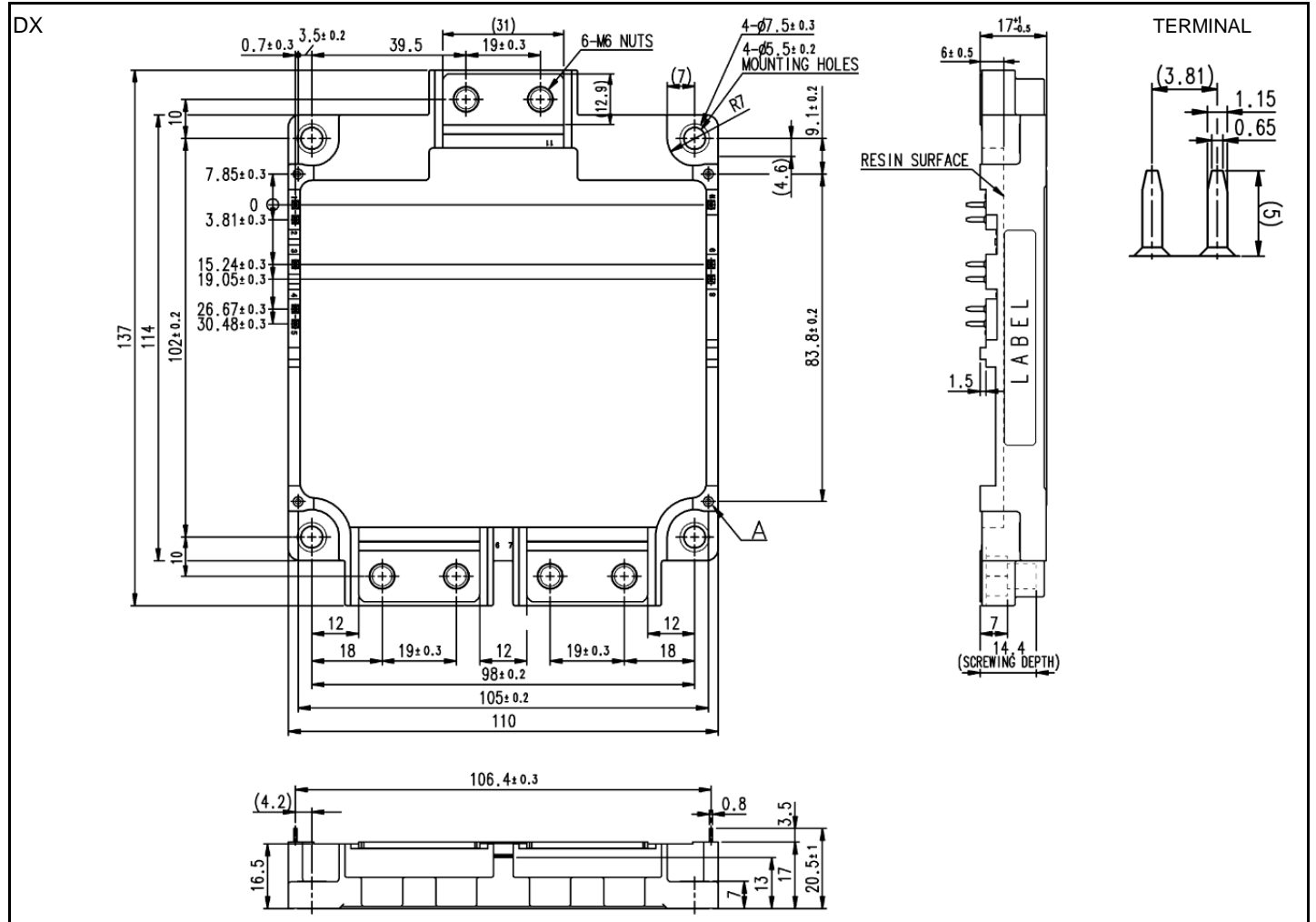


CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

OUTLINE DRAWING

Dimension in mm

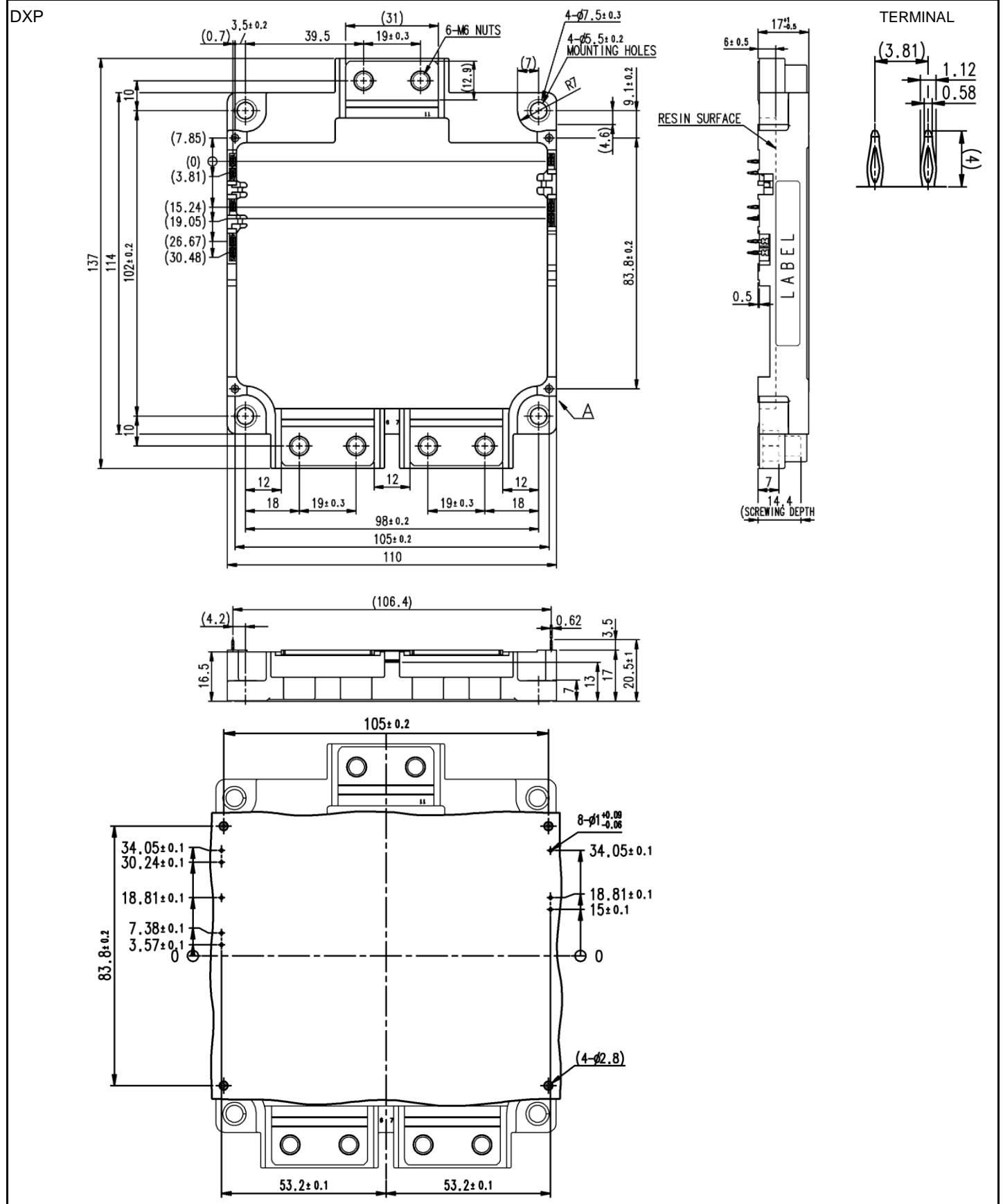


CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

OUTLINE DRAWING

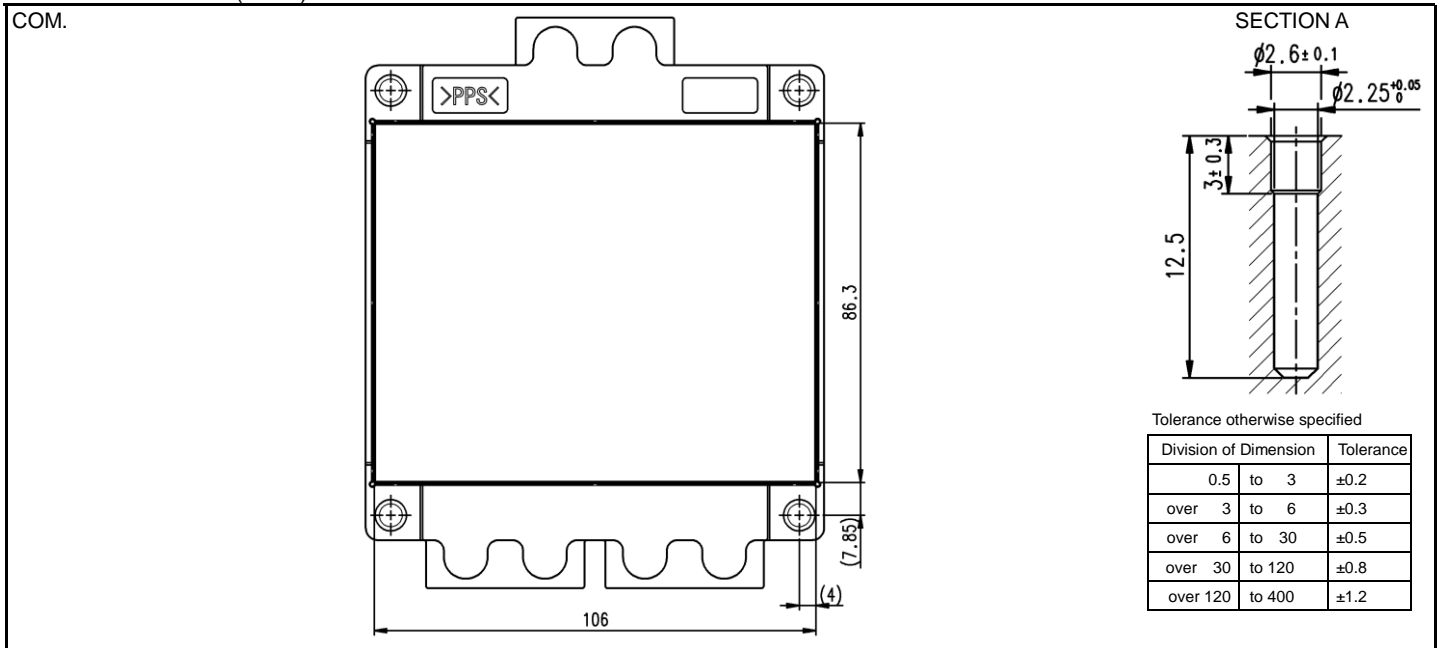
Dimension in mm



CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

OUTLINE DRAWING(Cont.)



MAXIMUM RATINGS ($T_{vj}=25\text{ }^{\circ}\text{C}$, unless otherwise specified)

INVERTER PART IGBT/FWD

Symbol	Item	Conditions	Rating	Unit
V_{CES}	Collector-emitter voltage	G-E short-circuited	1200	V
V_{GES}	Gate-emitter voltage	C-E short-circuited	± 20	V
I_C	Collector current	DC, $T_C=116\text{ }^{\circ}\text{C}$ (Note2, 4)	1000	A
I_{CRM}		Pulse, Repetitive (Note3)	2000	
P_{tot}	Total power dissipation	$T_C=25\text{ }^{\circ}\text{C}$ (Note2, 4)	5355	W
I_E (Note1)	Emitter current	DC (Note2)	1000	A
I_{ERM} (Note1)		Pulse, Repetitive (Note3)	2000	

MODULE

Symbol	Item	Conditions	Rating	Unit
V_{isol}	Isolation voltage	Terminals to base plate, RMS, $f=60\text{ Hz}$, AC 1 min	2500	V
T_{vjmax}	Maximum junction temperature	Instantaneous event (overload)	175	$^{\circ}\text{C}$
T_{Cmax}	Maximum case temperature	(Note4)	125	
T_{vjop}	Operating junction temperature	Continuous operation (under switching)	-40 ~ +150	$^{\circ}\text{C}$
T_{stg}	Storage temperature	-	-40 ~ +125	

CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE**ELECTRICAL CHARACTERISTICS (T_{vj}=25 °C, unless otherwise specified)**
INVERTER PART IGBT/FWD

Symbol	Item	Conditions	Limits			Unit	
			Min.	Typ.	Max.		
I _{CEs}	Collector-emitter cut-off current	V _{CE} =V _{CEs} , G-E short-circuited	-	-	1.0	mA	
I _{GES}	Gate-emitter leakage current	V _{GE} =V _{GES} , C-E short-circuited	-	-	0.5	μA	
V _{GE(th)}	Gate-emitter threshold voltage	I _C =100 mA, V _{CE} =10 V	5.4	6.0	6.6	V	
V _{CEsat} (Terminal)	Collector-emitter saturation voltage	I _C =1000 A, V _{GE} =15 V, Refer to the figure of test circuit (Note5)	T _{vj} =25 °C	-	1.55	1.95	V
			T _{vj} =125 °C	-	1.70	-	
			T _{vj} =150 °C	-	1.75	-	
V _{CEsat} (Chip)		I _C =1000 A, V _{GE} =15 V, (Note5)	T _{vj} =25 °C	-	1.50	1.75	V
			T _{vj} =125 °C	-	1.70	-	
			T _{vj} =150 °C	-	1.75	-	
C _{ies}	Input capacitance	V _{CE} =10 V, G-E short-circuited	-	-	242.5	nF	
C _{oes}	Output capacitance		-	-	6.8		
C _{res}	Reverse transfer capacitance		-	-	3.0		
Q _G	Gate charge	V _{CC} =600 V, I _C =1000 A, V _{GE} =15 V	-	7.5	-	μC	
t _{d(on)}	Turn-on delay time	V _{CC} =600 V, I _C =1000 A, V _{GE} =±15 V, R _G =2.0 Ω, Inductive load	-	-	800	ns	
t _r	Rise time		-	-	400		
t _{d(off)}	Turn-off delay time		-	-	1300		
t _f	Fall time		-	-	400		
V _{EC} (Note1) (Terminal)	Emitter-collector voltage	I _E =1000 A, G-E short-circuited, Refer to the figure of test circuit (Note5)	T _{vj} =25 °C	-	1.65	2.15	V
			T _{vj} =125 °C	-	1.75	-	
			T _{vj} =150 °C	-	1.80	-	
V _{EC} (Note1) (Chip)		I _E =1000 A, G-E short-circuited, (Note5)	T _{vj} =25 °C	-	1.60	1.95	V
			T _{vj} =125 °C	-	1.60	-	
			T _{vj} =150 °C	-	1.60	-	
t _{rr} (Note1)	Reverse recovery time	V _{CC} =600 V, I _E =1000 A, V _{GE} =±15 V, R _G =2.0 Ω, Inductive load	-	-	500	ns	
Q _{rr} (Note1)	Reverse recovery charge		-	78	-	μC	
E _{on}	Turn-on switching energy per pulse	V _{CC} =600 V, I _C =I _E =1000 A,	-	150.5	-	mJ	
E _{off}	Turn-off switching energy per pulse	V _{GE} =±15 V, R _G =2.0 Ω, T _{vj} =150 °C, Inductive load	-	128.4	-		
E _{rr} (Note1)	Reverse recovery energy per pulse		-	69	-	mJ	
R _{CC+EE}	Internal lead resistance	Main terminals-chip, per switch, T _C =25 °C (Note4)	-	0.5	-	mΩ	
r _g	Internal gate resistance	Per switch	-	0.4	-	Ω	

NTC THERMISTOR PART

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R ₂₅	Zero-power resistance	T _C =25 °C (Note4)	4.85	5.00	5.15	kΩ
ΔR/R	Deviation of resistance	R ₁₀₀ =493 Ω, T _C =100 °C (Note4)	-7.3	-	+7.8	%
B _(25/50)	B-constant	Approximate by equation (Note6)	-	3375	-	K
P ₂₅	Power dissipation	T _C =25 °C (Note4)	-	-	10	mW

THERMAL RESISTANCE CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
R _{th(j-c)Q}	Thermal resistance	Junction to case, per Inverter IGBT (Note4)	-	-	28	K/kW
R _{th(j-c)D}		Junction to case, per Inverter FWD (Note4)	-	-	49	
R _{th(c-s)}	Contact thermal resistance	Case to heat sink,	-	7.1	-	K/kW
		Thermal grease applied (Note4, 7) per 1 module, PC-TIM applied (Note4, 8)				

CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

MECHANICAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			Unit	
			Min.	Typ.	Max.		
M _t	Mounting torque	Main terminals M 6 screw	3.5	4.0	4.5	N·m	
M _s	Mounting torque	Mounting to heat sink M 5 screw	2.5	3.0	3.5	N·m	
d _s	Creepage distance	Solder pin type (DX)	Terminal to terminal	17.3	-	-	mm
			Terminal to base plate	17.5	-	-	
		Pressfit pin type (DXP)	Terminal to terminal	16.5	-	-	mm
			Terminal to base plate	18.0	-	-	
d _a	Clearance	Solder pin type (DX)	Terminal to terminal	10.3	-	-	mm
			Terminal to base plate	11.7	-	-	
		Pressfit pin type (DXP)	Terminal to terminal	10.2	-	-	mm
			Terminal to base plate	11.8	-	-	
e _c	Flatness of base plate	On the centerline X, Y (Note9)	±0	-	+200	μm	
m	mass	-	-	490	-	g	

*: This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU.

Note1. Represent ratings and characteristics of the anti-parallel, emitter-collector free-wheeling diode (FWD).

- Junction temperature (T_{vj}) should not increase beyond T_{vjmax} rating.
- Pulse width and repetition rate should be such that the device junction temperature (T_{vj}) dose not exceed T_{vjmax} rating.
- Case temperature (T_c) and heat sink temperature (T_s) are defined on the each surface (mounting side) of base plate and heat sink just under the chips.
Refer to the figure of chip location.

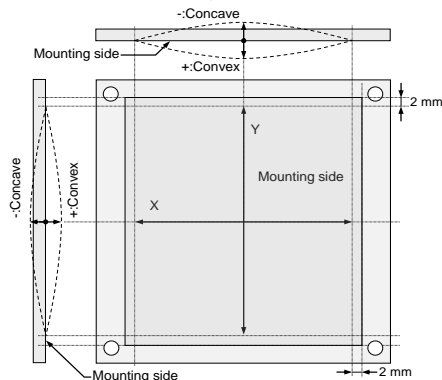
- Pulse width and repetition rate should be such as to cause negligible temperature rise. Refer to the figure of test circuit.

$$B_{(25/50)} = \ln \left(\frac{R_{25}}{R_{50}} \right) \left(\frac{1}{T_{25}} - \frac{1}{T_{50}} \right)$$

R₂₅: resistance at absolute temperature T₂₅ [K]; T₂₅=25 [°C]+273.15=298.15 [K]

R₅₀: resistance at absolute temperature T₅₀ [K]; T₅₀=50 [°C]+273.15=323.15 [K]

- Typical value is measured by using thermally conductive grease of λ=0.9 W/(m·K)/D_(c-s)=50 μm.
- Typical value is measured by using PC-TIM of λ=3.4 W/(m·K)/D_(c-s)=50 μm.
- The base plate (mounting side) flatness measurement points (X, Y) are shown in the following figure.



- Use the following screws when mounting the printed circuit board (PCB) on the standoffs.

PCB thickness : t1.6

Type	Manufacturer	Size	Tightening torque (N·m)	Recommended tightening method
(1) PT®	EJOT	K25x8	0.55 ± 0.055	by handwork (equivalent to 30 rpm by mechanical screw driver) ~ 600 rpm (by mechanical screw driver)
(2) PT®		K25x10	0.75 ± 0.075 N·m	
(3) DELTA PT®		25x8	0.55 ± 0.055 N·m	
(4) DELTA PT®		25x10	0.75 ± 0.075 N·m	
(5) B1 tapping screw	-	φ2.6x10	0.75 ± 0.075 N·m	
		φ2.6x12		

RECOMMENDED OPERATING CONDITIONS

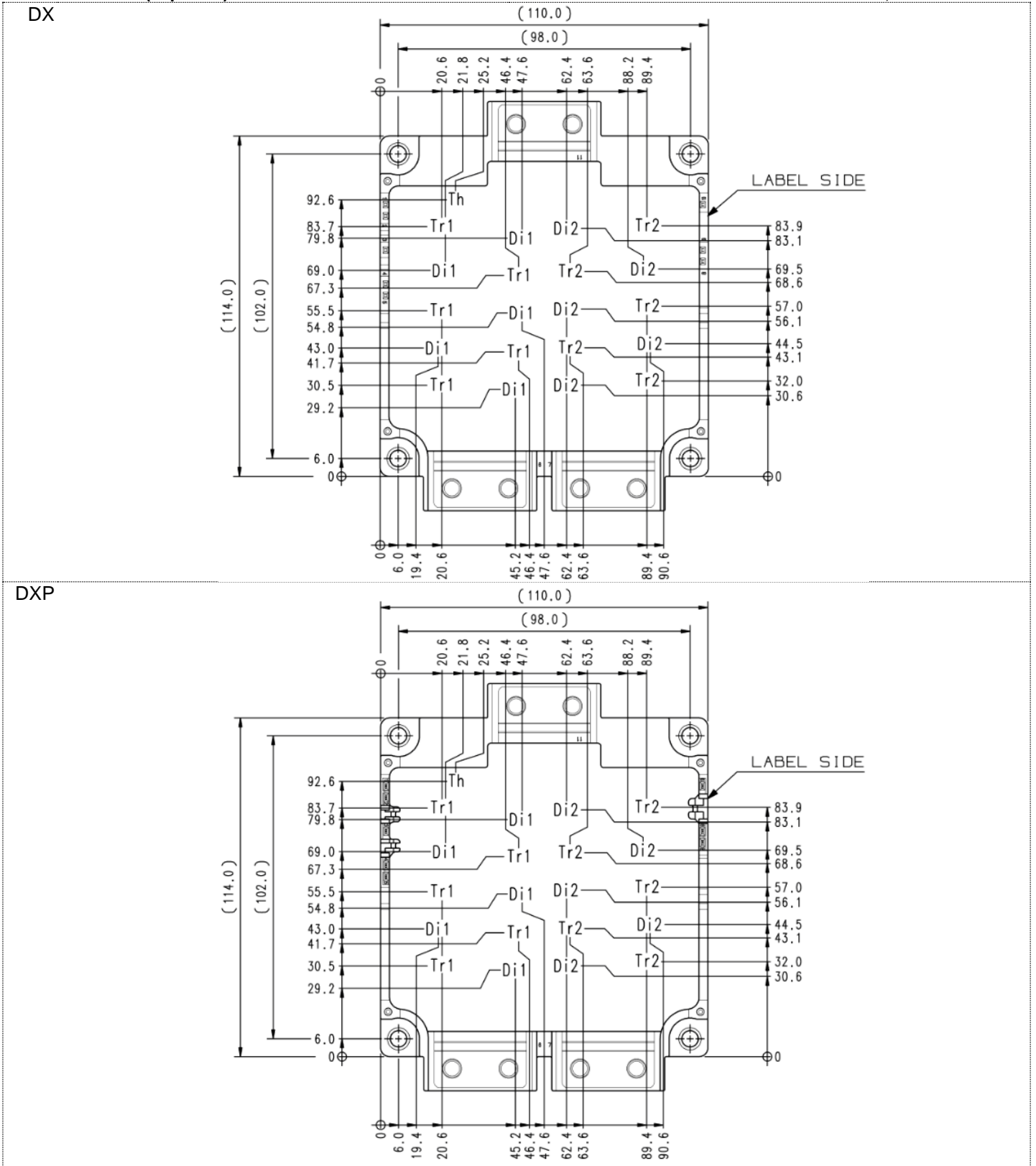
Symbol	Item	Conditions	Limits			Unit
			Min.	Typ.	Max.	
V _{CC}	(DC) Supply voltage	Applied across C1-E2 terminals	-	600	850	V
V _{GEon}	Gate (-emitter drive) voltage	Applied across G1-E1s/G2-E2s terminals	13.5	15.0	16.5	V
R _G	External gate resistance	Per switch	2.0	-	20	Ω

CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

CHIP LOCATION (Top view)

Dimension in mm, tolerance: ± 1 mm



Tr1/Tr2: IGBT, Di1/Di2: FWD, Th: NTC thermistor

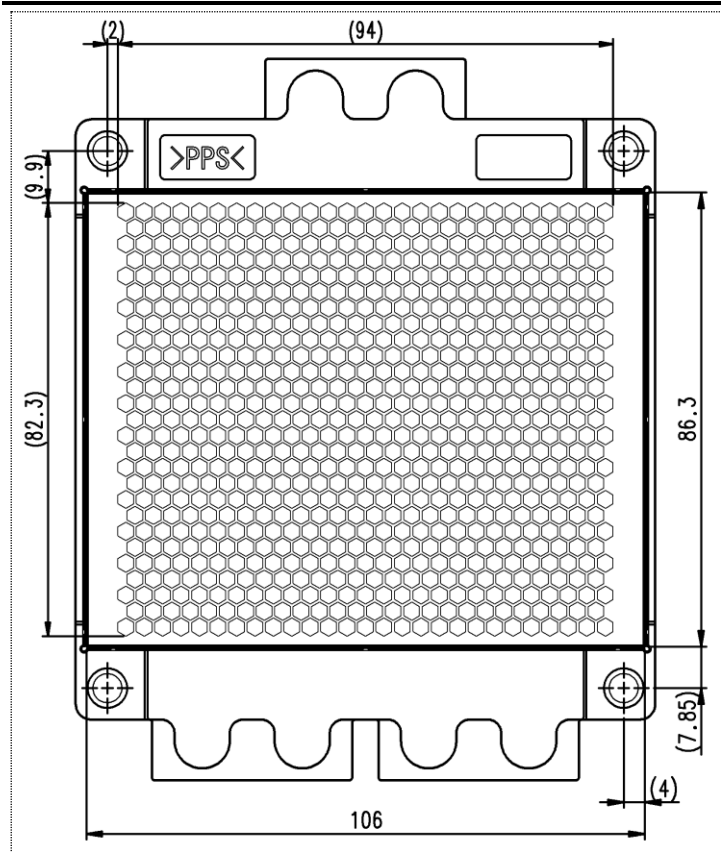
Option: PC-TIM applied baseplate outline

<IGBT Modules>

CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE

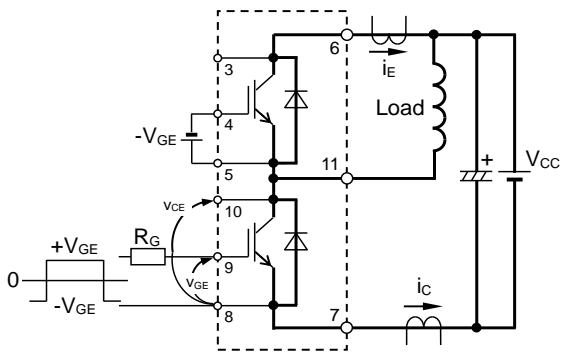
INSULATED TYPE



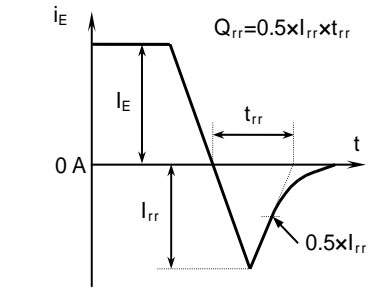
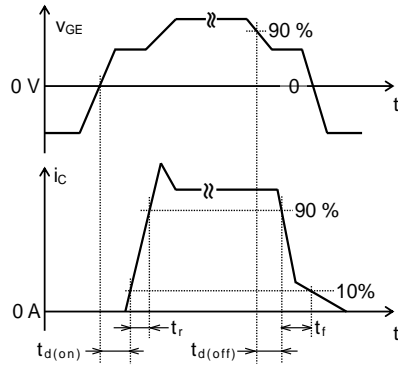
CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

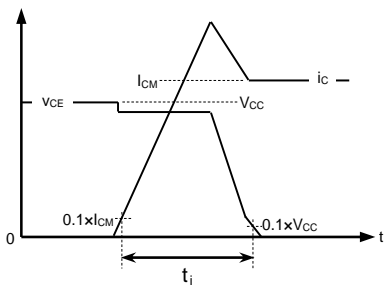
TEST CIRCUIT AND WAVEFORMS



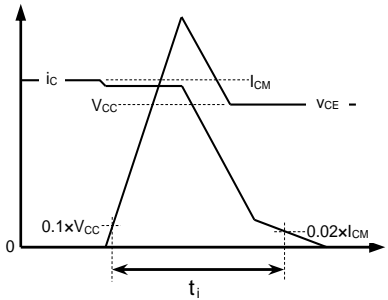
Switching characteristics test circuit and waveforms



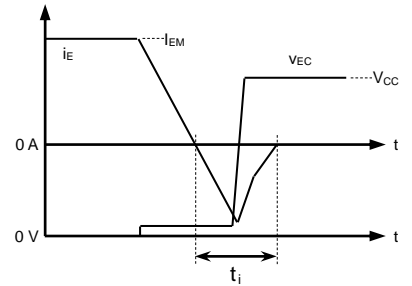
t_{rr} , Q_{rr} characteristics test waveform



IGBT Turn-on switching energy



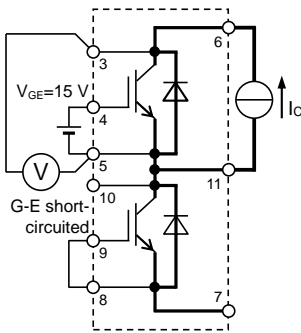
IGBT Turn-off switching energy



FWD Reverse recovery energy

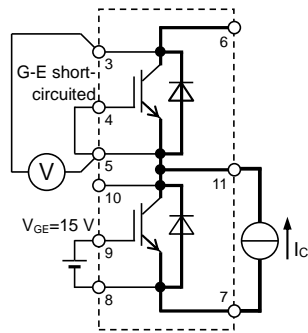
Switching energy and Reverse recovery energy test waveforms (Integral time instruction drawing)

TEST CIRCUIT

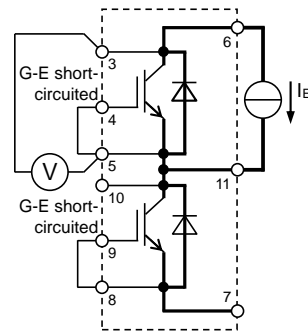


Tr1

V_{CEsat} characteristics test circuit

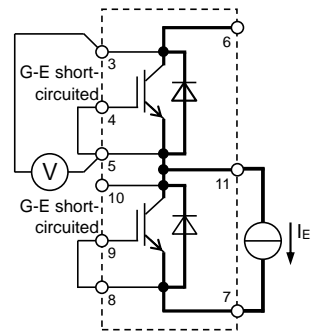


Tr2



Di1

V_{EC} characteristics test circuit

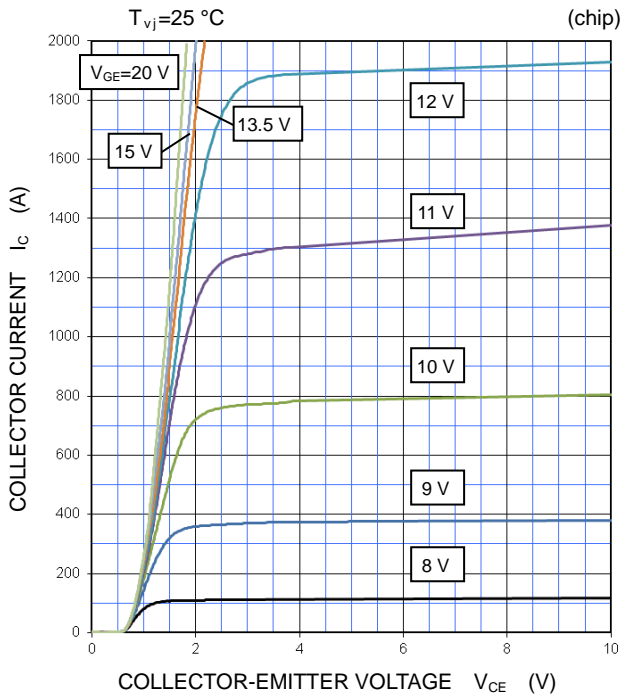


Di2

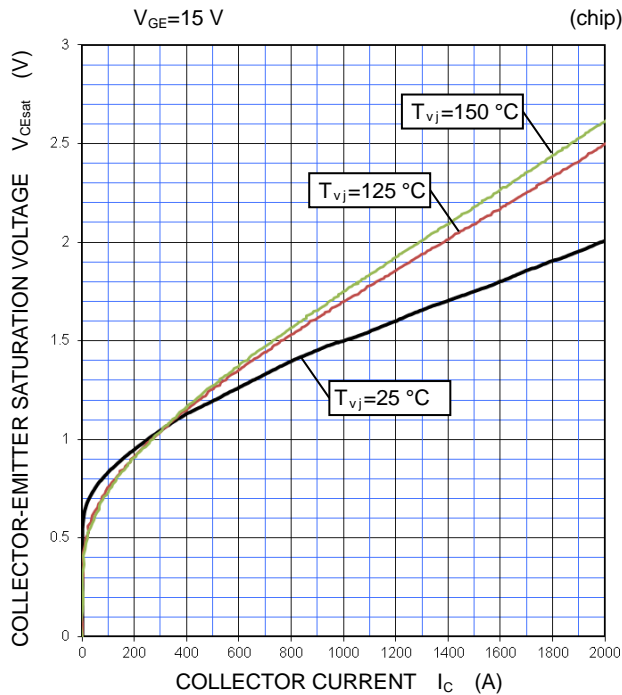
PERFORMANCE CURVES

INVERTER PART

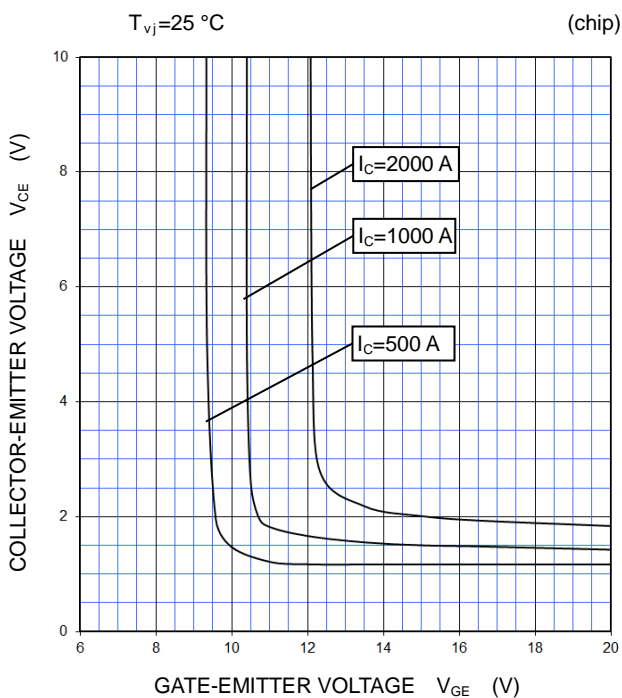
OUTPUT CHARACTERISTICS (TYPICAL)



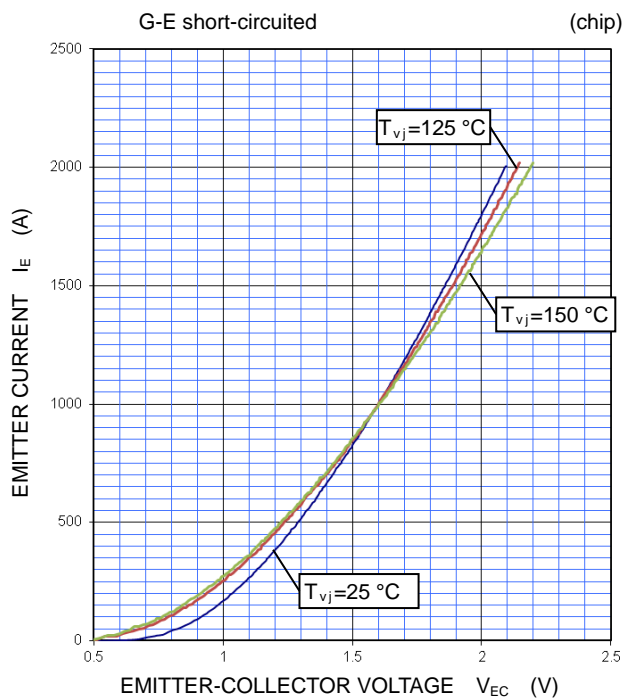
COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



COLLECTOR-EMITTER VOLTAGE CHARACTERISTICS (TYPICAL)



FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



CM1000DX-24T/CM1000DXP-24T

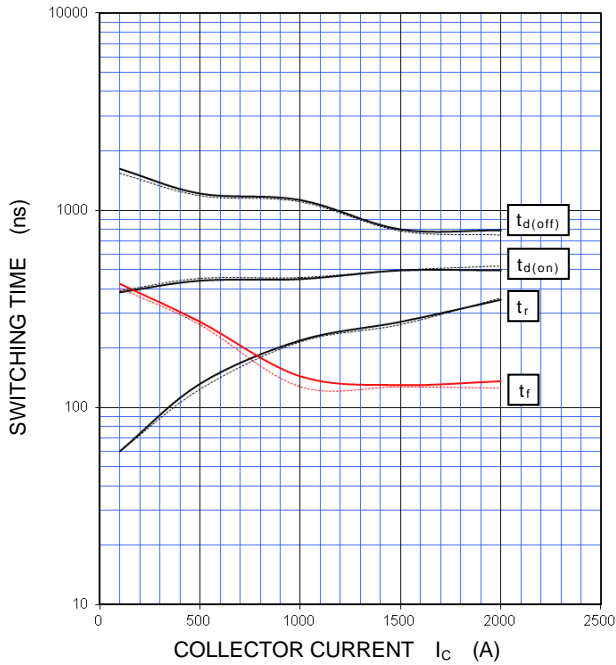
HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

INVERTER PART

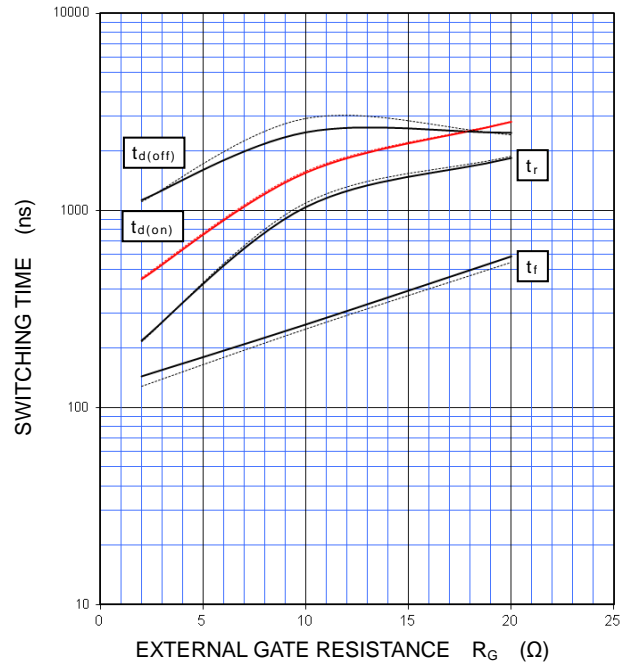
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)

$V_{CC}=600\text{ V}$, $R_G=2.0\ \Omega$, $V_{GE}=\pm 15\text{ V}$, INDUCTIVE LOAD
 —: $T_{vj}=150\text{ }^\circ\text{C}$, - - - -: $T_{vj}=125\text{ }^\circ\text{C}$



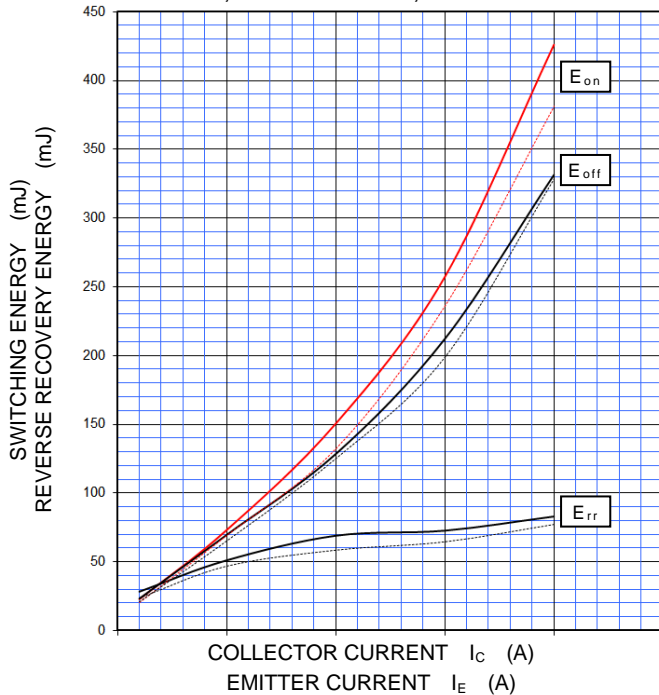
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)

$V_{CC}=600\text{ V}$, $I_C=1000\text{ A}$, $V_{GE}=\pm 15\text{ V}$, INDUCTIVE LOAD
 —: $T_{vj}=150\text{ }^\circ\text{C}$, - - - -: $T_{vj}=125\text{ }^\circ\text{C}$



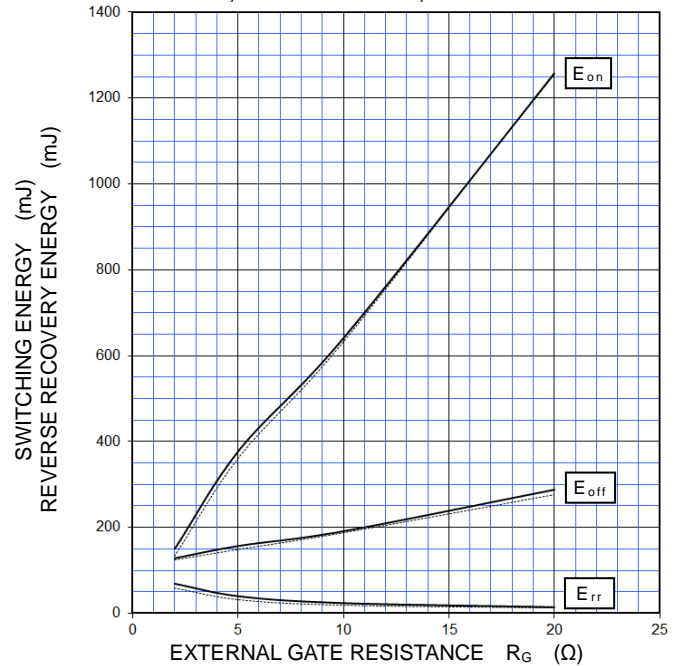
HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)

$V_{CC}=600\text{ V}$, $R_G=2.0\ \Omega$, $V_{GE}=\pm 15\text{ V}$, INDUCTIVE LOAD,
 —: $T_{vj}=150\text{ }^\circ\text{C}$, - - - -: $T_{vj}=125\text{ }^\circ\text{C}$, PER PULSE



HALF-BRIDGE SWITCHING CHARACTERISTICS (TYPICAL)

$V_{CC}=600\text{ V}$, $I_C/I_E=1000\text{ A}$, $V_{GE}=\pm 15\text{ V}$, INDUCTIVE LOAD,
 —: $T_{vj}=150\text{ }^\circ\text{C}$, - - - -: $T_{vj}=125\text{ }^\circ\text{C}$, PER PULSE



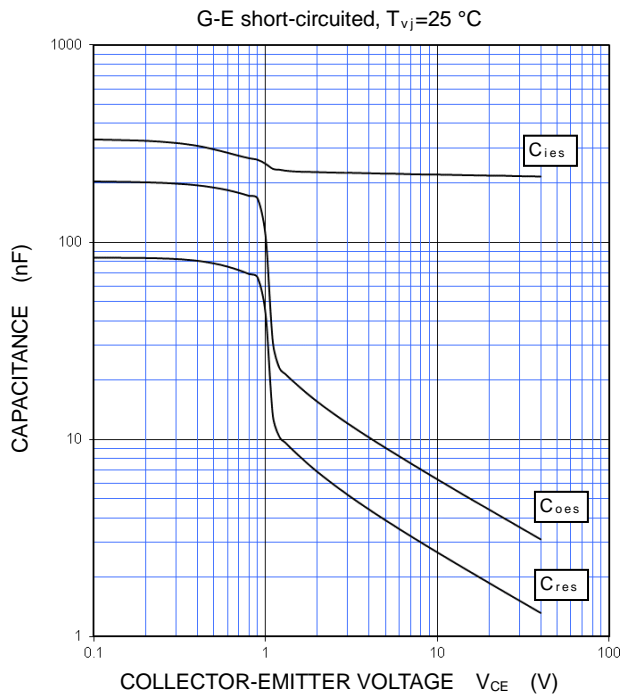
CM1000DX-24T/CM1000DXP-24T

HIGH POWER SWITCHING USE
INSULATED TYPE

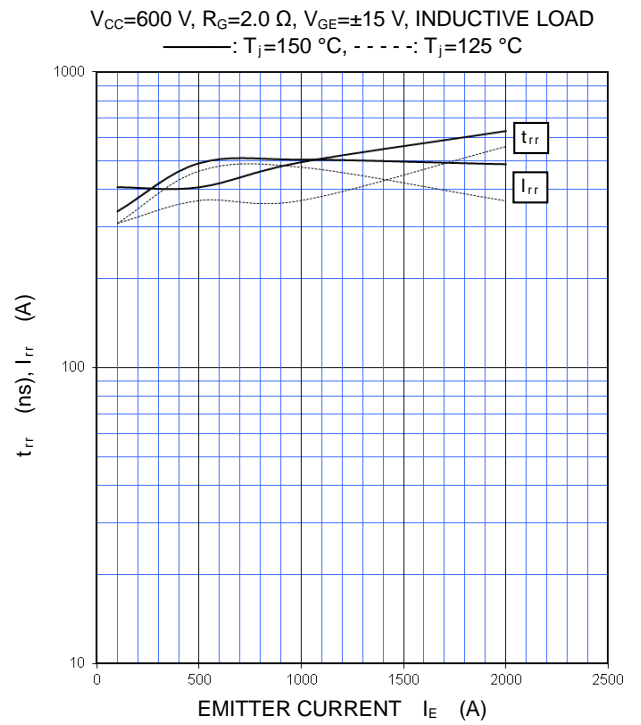
PERFORMANCE CURVES

INVERTER PART

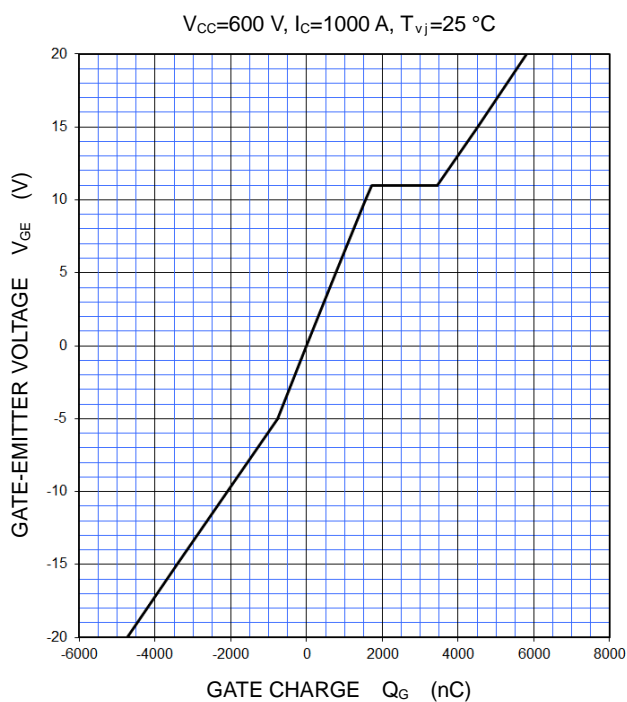
CAPACITANCE CHARACTERISTICS (TYPICAL)



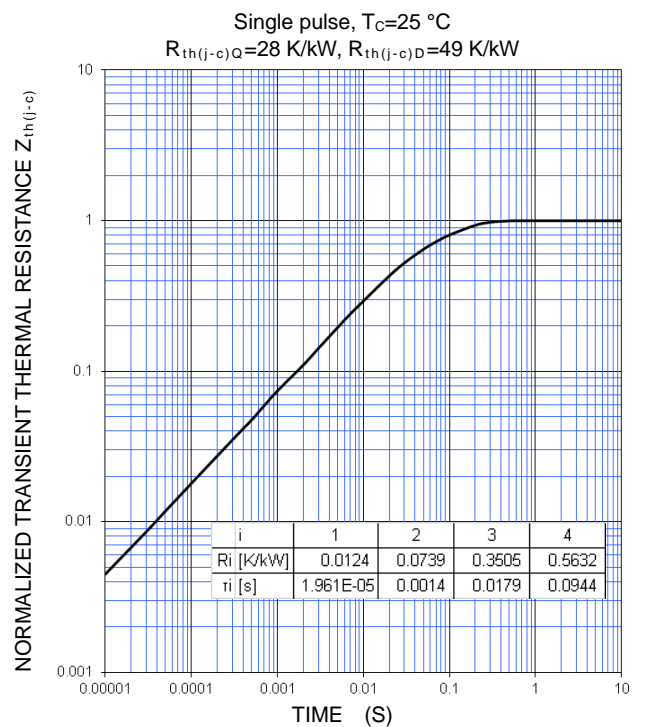
FREE WHEELING DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



GATE CHARGE CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (MAXIMUM)



CM1000DX-24T/CM1000DXP-24T

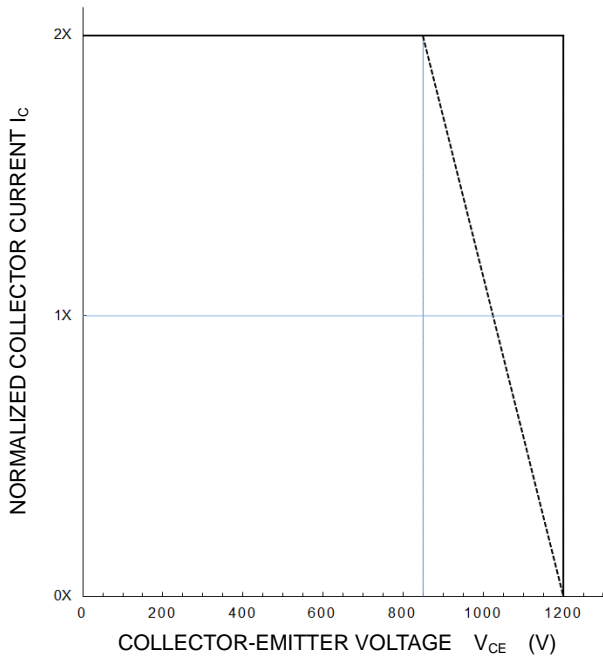
HIGH POWER SWITCHING USE
INSULATED TYPE

PERFORMANCE CURVES

INVERTER PART

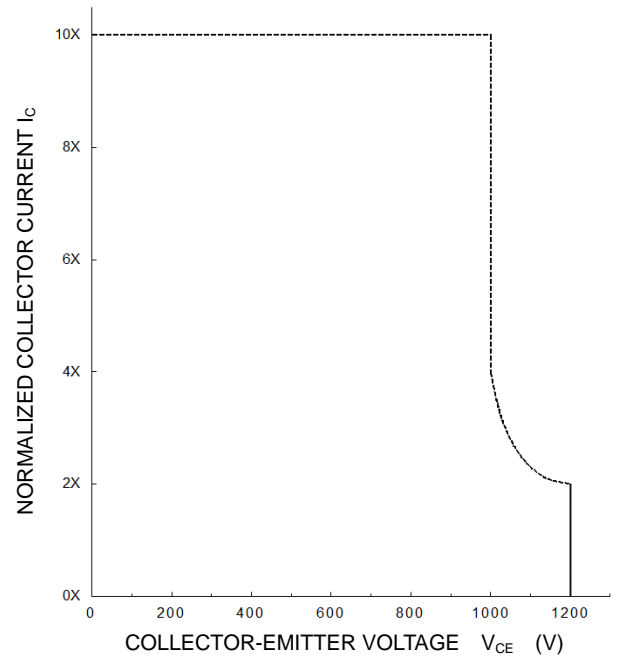
**TURN-OFF SWITCHING SAFE OPERATING AREA
(REVERSE BIAS SAFE OPERATING AREA)
(MAXIMUM)**

$V_{CC} \leq 850 \text{ V}$, $R_G = 2.0 \sim 20 \ \Omega$, $V_{GE} = \pm 15 \text{ V}$,
 ———: $T_{vj} = 25 \sim 150 \text{ }^\circ\text{C}$ (Normal load operations (Continuous))
 - - - - -: $T_{vj} = 175 \text{ }^\circ\text{C}$ (Unusual load operations (Limited period))



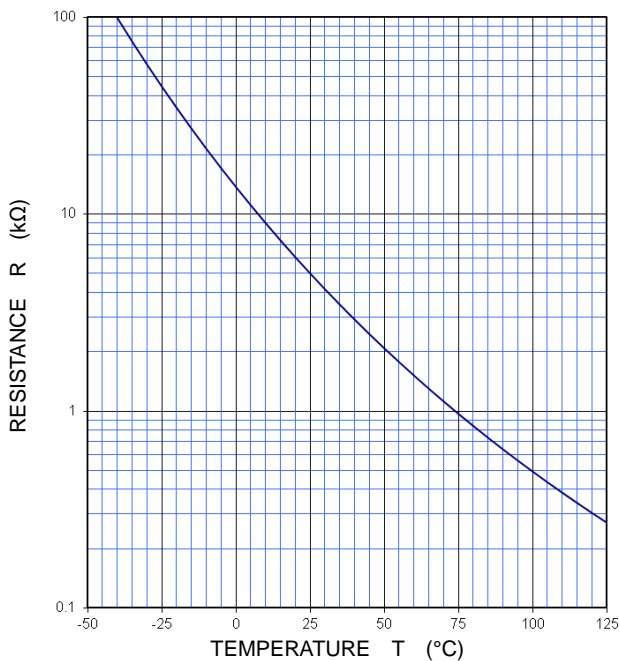
**SHORT-CIRCUIT SAFE OPERATING AREA
(MAXIMUM)**

$V_{CC} \leq 800 \text{ V}$, $R_G = 2.0 \sim 20 \ \Omega$, $V_{GE} = \pm 15 \text{ V}$,
 $T_{vj} = 25 \sim 150 \text{ }^\circ\text{C}$, $t_W \leq 8 \ \mu\text{s}$, Non-Repetitive



NTC thermistor part

**TEMPERATURE CHARACTERISTICS
(TYPICAL)**



Note: The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Keep safety first in your circuit designs!

This product is designed for industrial application purpose. The performance, the quality and support level of the product is guaranteed by "Customer's Std. Spec."

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